

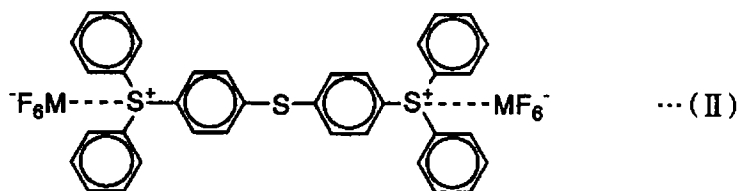
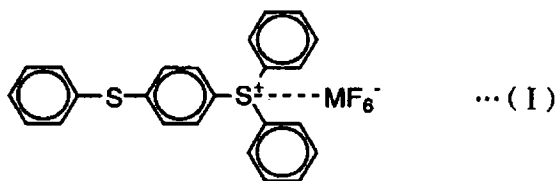
Amendments to and listing of the claims:

Please cancel claim 4 so that the claims read as follows:

1. (Previously Presented) A resin composition for stereolithography, which is an actinic radiation-curable resin composition comprising:

a cationic-polymerizable organic compound;
a radical-polymerizable organic compound;
a photo initiator for cationic polymerization; and
a photo initiator for radical polymerization,

wherein the photo initiator for cationic polymerization comprises a compound represented by the following formula (I), the compound having a purity of 97% or higher and containing less than 3% by mass of a compound represented by the following formula (II):



wherein M represents an antimony atom or a phosphorus atom; and the broken line between S⁺ and MF₆⁻ represents an ionic bond.

2. (Canceled)

3. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, wherein M in the compound represented by the formula (I) is an antimony atom.
4. (Canceled)
5. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, wherein the cationic-polymerizable organic compound comprises at least one compound having an epoxy group.
6. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, wherein the radical-polymerizable organic compound comprises at least one compound having a (meth)acryl group.
7. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, which comprises an oxetane compound at a ratio of from 1 to 30% by mass with respect to the mass of the cationic-polymerizable organic compound.
8. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, which comprises a polyalkylene ether compound at a ratio of from 1 to 30% by mass with respect to the mass of the cationic-polymerizable organic compound.
9. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, wherein a concentration of diphenyl sulfoxide in the compound represented by formula (I) is less than 0.05% by mass.
10. (Previously Presented) The resin composition for stereolithography as claimed in claim 1, wherein the photoinitiator for cationic polymerization contains substantially no compound represented by formula (II).